

Process Name/ Title:

SOLDERING-Solder wire supply

Document No:

WI-PRO-SHM-021

April 23, 2025

WORK INSTRUCTION
Product Code/Name: Customer Code:

Effective Date:

Page No.:

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1 of 1

No.

Work Procedure/ Illustration

ALL

Records/Remarks/ Quality Pointers

Lead Free solder has poor wettability and spreadability, because it is easily oxidized and has high surface tension.

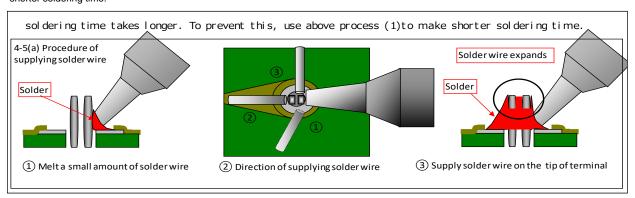
Soldering time takes longer, because of that,there is a possibility of huge amount of flux formation after soldering.

1 METHOD OF SUPPLYING SOLDER WIRE & PREVENTION OF FLUX ACCUMULATION (4-5(a))

- (1) Put solder wire directly on the iron, and supply solder wire constantly
- (little by little), it must form a heat bridge. (4-5(a)1)
- (2) Move and supply solder wire based on the direction shown at (4-5(a)2)
- (3) Supply solder wire to expand the whole terminal. (4-5(a)3)

2 CONTROL OF SOLDERING TIME & POSITION

Since, Pb free's melting point is higher 32~37°C than lead (Sn-37Pb), therefore soldering time takes longer. To prevent this, use above process (1)to make shorter soldering time.

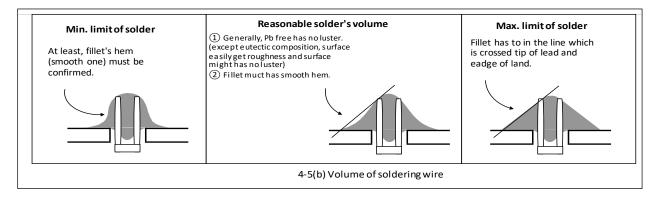


3 CONTROL OF VOLUME

Below chart 4-5(b) shows limit samples of volume quantity.

4 CONTROL OF SOLDER WIRE SUPPLY

- 1. To prevent weak connection if solder supply is not enough.
- 2. To prevent crack and other defects such as excessive flux formation if solder supply is too much.



						Prepare	Check	Approve
						N 1	0 1	
4/23/2025	1	Change Customer code	L.Famodulan	A.Ayop	W.Carbillon	Donadala	(None	(salsh
7/1/2017	0	Previously established Work Instruction from NBC Japan (for history purpose only)	A. Yocor	O. Merin	T. Suguyama	L.Fampdulan	A.Ayer	W.¢arbillon
Eff./Rev. Date	Rev. No.	Details of change	Revise	Check	Approve	Est. date:	July 1	, 2017